

# ACE114480B N-Channel Enhancement Mode Power MOSFET

#### **Description**

- DC/DC conversion
- Battery protection
- Load switching
- DC/AC inverters

#### **Features**

- V<sub>DS</sub>=40V
- I<sub>D</sub>=61.7A
- $R_{DS(ON)}@V_{GS}=10V$ , TYP 3.7m $\Omega$
- $R_{DS(ON)}@V_{GS}=4.5V$ , TYP 5.6m $\Omega$

#### Absolute Maximum Ratings @TA=25°C unless otherwise noted

Parameter		Symbol	Max	Unit	
Drain-Source Voltage		$V_{DSS}$	40	V	
Gate-Source Voltage		$V_{GSS}$	±20	V	
D : 0	T <sub>C</sub> =25°C		61.7		
Drain Current (Continuous)*C	T <sub>C</sub> =70°C	l <sub>D</sub>	49.4	Α	
Drain Current (Pulsed)*B		I <sub>DM</sub>	247	Α	
Power Dissipation	T <sub>C</sub> =25°C	P <sub>D</sub>	34.7	W	
Operating temperature / storage temperature		T <sub>J</sub> /T <sub>STG</sub>	-55~150	°C	

#### **Thermal Resistance Ratings**

Parameter		Symbol	Maximum	Unit
Maximum Junction-to-Ambient *A	Steady State	$R_{thJA}$	70	°C // /
Maximum Junction-to-Case (Drain)	Steady State	ite R <sub>thJC</sub> 3.6		

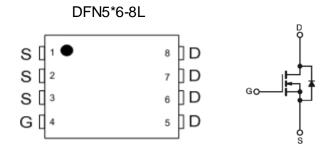
A: The value of  $R_{\theta JA}$  is measured with the device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A$ =25°C. The value in any given application depends on the user's specific board design.

- B: Repetitive rating, pulse width limited by junction temperature.
- C: The current rating is based on the  $t \le 10s$  junction to ambient thermal resistance rating.

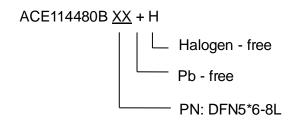


### **N-Channel Enhancement Mode Power MOSFET**

## **Packaging Type**



## **Ordering information**





### **N-Channel Enhancement Mode Power MOSFET**

## **Electrical Characteristics** T<sub>A</sub>=25°C, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static *B							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250 \mu A$	40			V	
Zero Gate Voltage Drain Current	I <sub>DSS1</sub>	$V_{DS} = 32V, V_{GS} = 0V$			1	μΑ	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}$ , $I_{DS} = 250 \mu A$	1		2.5	V	
Gate Leakage Current	$I_{GSS}$	$V_{GS}$ = ±20 $V$ , $V_{DS}$ =0 $V$			±100	nA	
Drain-Source On-state Resistance	R <sub>DS(on)</sub>	$V_{GS} = 10V, I_{D} = 12A$		3.7	4.8	mΩ	
	R <sub>DS(on)</sub>	$V_{GS} = 4.5V, I_{D} = 8A$		5.6	7.3		
Diode Forward Voltage	$V_{SD}$	$I_{SD}$ =1A, $V_{GS}$ = 0V			1.2	<b>V</b>	
Diode Forward Current *A	Is	T <sub>C</sub> =25°C			28.9	Α	
Switching							
Total Gate Charge	$Q_g$	V 00V I 00A		22.7		nC	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 20V, I_{D} = 20A,$ $V_{GS} = 10V$		4		nC	
Gate-Drain Charge	$Q_{gd}$	VGS= 10V		5.34		nC	
Turn-on Delay Time	t <sub>d(on)</sub>	V 20V I 20A		5.4		ns	
Turn-on Rise Time	t <sub>r</sub>	$V_{DS} = 20V, I_{DS} = 20A,$		40.3		ns	
Turn-off Delay Time	t <sub>d(off)</sub>	$V_{GEN}$ = 10V, $R_{G}$ = 3.9 $\Omega$ $R_{L}$ = 1 $\Omega$		25.2		ns	
Turn-off Fall Time	t <sub>f</sub>	1\[- 1\2		23.5		ns	
Dynamic							
Input Capacitance	C <sub>iss</sub>	V 20V V 0V		932.7		pF	
Output Capacitance	Coss	$V_{DS}$ =20V, $V_{GS}$ = 0V, f= 1.0MHz		421		pF	
Reverse Transfer Capacitance	$C_{rss}$	I= 1.UIVII IZ		49.7		pF	

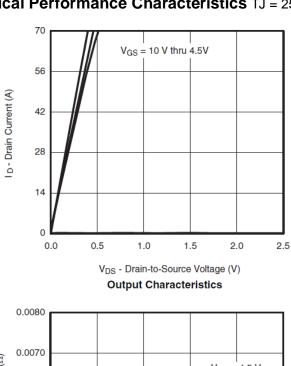
A: The current rating is based on the t≤ 10s junction to ambient thermal resistance rating.

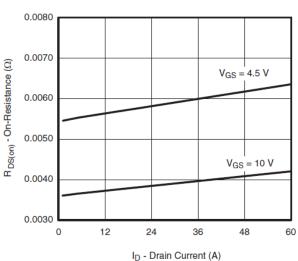
B: Pulse Test: Pulse Wide≤ 300µs , Duty Cycle≤ 2%.



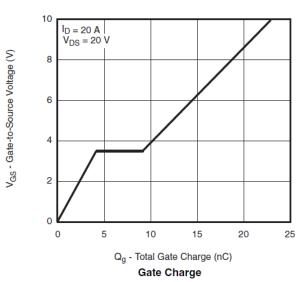
#### **N-Channel Enhancement Mode Power MOSFET**

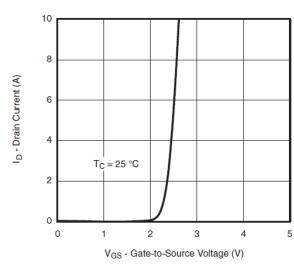
## Typical Performance Characteristics TJ = 25 °C, unless otherwise noted

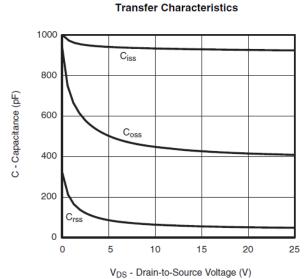


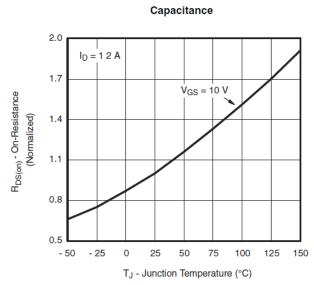








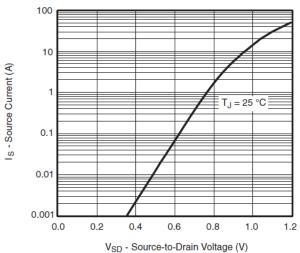




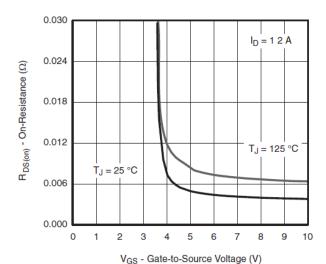
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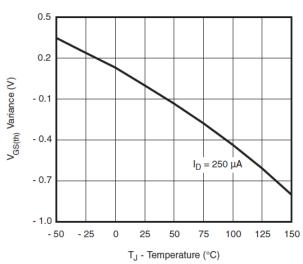
#### **N-Channel Enhancement Mode Power MOSFET**



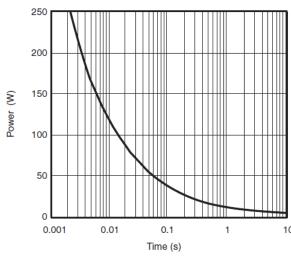
Source-Drain Diode Forward Voltage



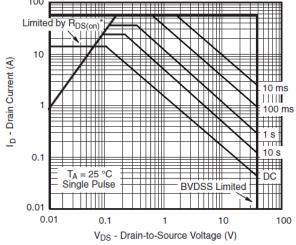
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power (Junction-to-Ambient)

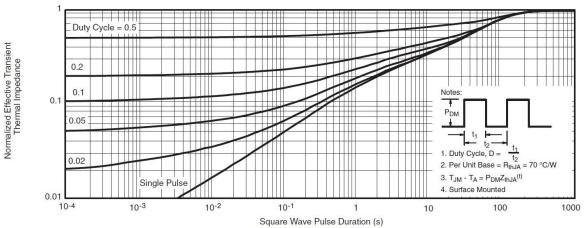


\*  $V_{GS} > \mbox{minimum } V_{GS}$  at which  $R_{DS(on)}$  is specified

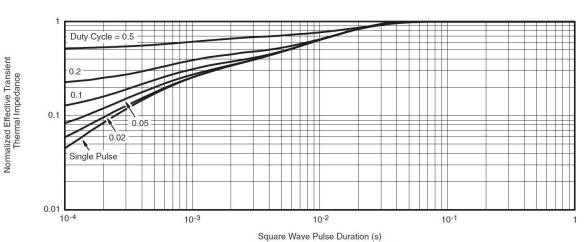
Safe Operating Area, Junction-to-Ambient



#### **N-Channel Enhancement Mode Power MOSFET**



Normalized Thermal Transient Impedance, Junction-to-Ambient



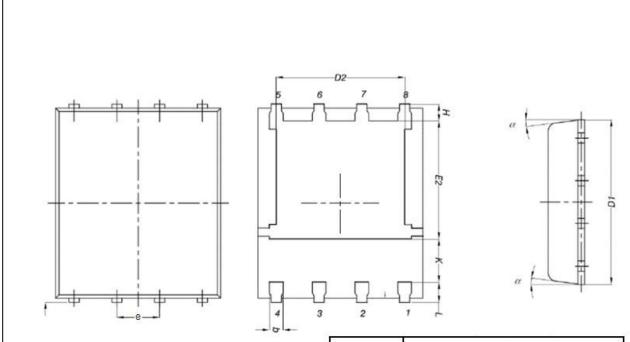
Normalized Thermal Transient Impedance, Junction-to-Case

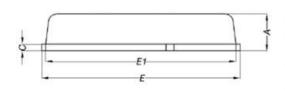


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## **Packing Information**

## DFN5\*6-EP





DIM	MILLIMETERS				
	MIN.	NOM.	MAX.		
A	0.8		1.1		
b	0.2	1000	0.51		
С	0.15	(2)2)	0.35		
D1	4.8	(#(#)	5.3		
D2	3.61	1227.231	4.15		
E	5.85		6.3		
E1	5.45	777	6		
E2	3.3	2223	4.2		
e		1.27			
Н	0.41	10.70	0.71		
K	1.1	12/21	1.5		
L	0.45	#(=)	0.74		
а	0°	<u> 1000 (100</u>	12°		



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#### Notes

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- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and shoes failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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